

Title (en)  
FORMALDEHYDE-FREE ELECTROLESS COPPER PLATING SOLUTION

Title (de)  
FORMALDEHYDFREIE LÖSUNG FÜR STROMLOSE VERKUPFERUNG

Title (fr)  
SOLUTION POUR CUIVRAGE AUTOCATALYTIQUE EXEMPTÉ DE FORMALDÉHYDE

Publication  
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Application  
**EP 12766668 A 20121001**

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Abstract (en)  
[origin: WO2013050332A2] The invention relates to an electroless aqueous copper plating solution, comprising a source of copper ions, a source of glyoxylic acid as reducing agent, and at least one polyamino disuccinic acid or at least one polyamino monosuccinic acid, or a mixture of at least one polyamino disuccinic acid and at least one polyamino monosuccinic acid as complexing agent, as well as to a method for electroless copper plating utilizing said solution and the use of the solution for the plating of substrates.

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**C23C 18/40** (2006.01)

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